

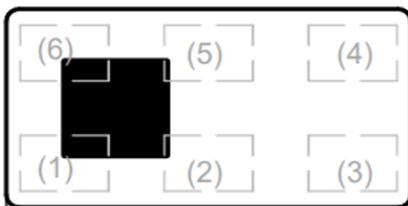
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

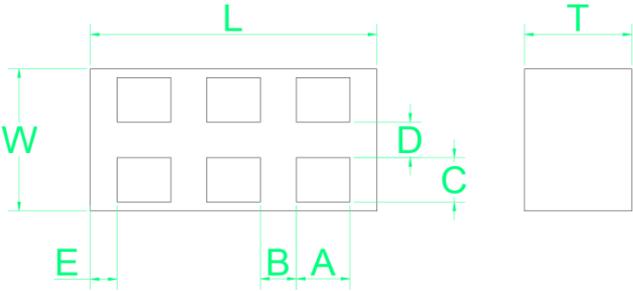
NO.	Parameter		SPEC	
			25°C	-40~90°C
1	Insertion Loss (f1)	2400~2500 MHz	0.6 dB	0.8 dB
	Insertion Loss (f2)	4900~5100 MHz	1.4 dB	1.7 dB
		5150~5950 MHz	1.2 dB	1.5 dB
2	Attenuation (f1)	4800~5000 MHz	35 dB	35 dB
		7200~7500 MHz	15 dB	15 dB
	Attenuation (f2)	2400~2500 MHz	15 dB	15 dB
		3400~3600 MHz	15 dB	15 dB
		3600~3800 MHz	10 dB	10 dB
		6900~7200 MHz	15 dB	15 dB
		7200~7800 MHz	25 dB	25 dB
		10300~11700 MHz	15 dB	15 dB
15300~16200 MHz	15 dB	15 dB		
3	Return Loss (In BW)	10 dB		
4	Isolation	2400~2500 MHz	40 dB	40 dB
		4900~5100 MHz	35 dB	35 dB
		5150~5950 MHz	32 dB	32 dB
5	Port Impedance	50Ω		
6	Power	1.0 W max.		
7	Operation Temperature Range	-40°C ~ +90°C		

Construction

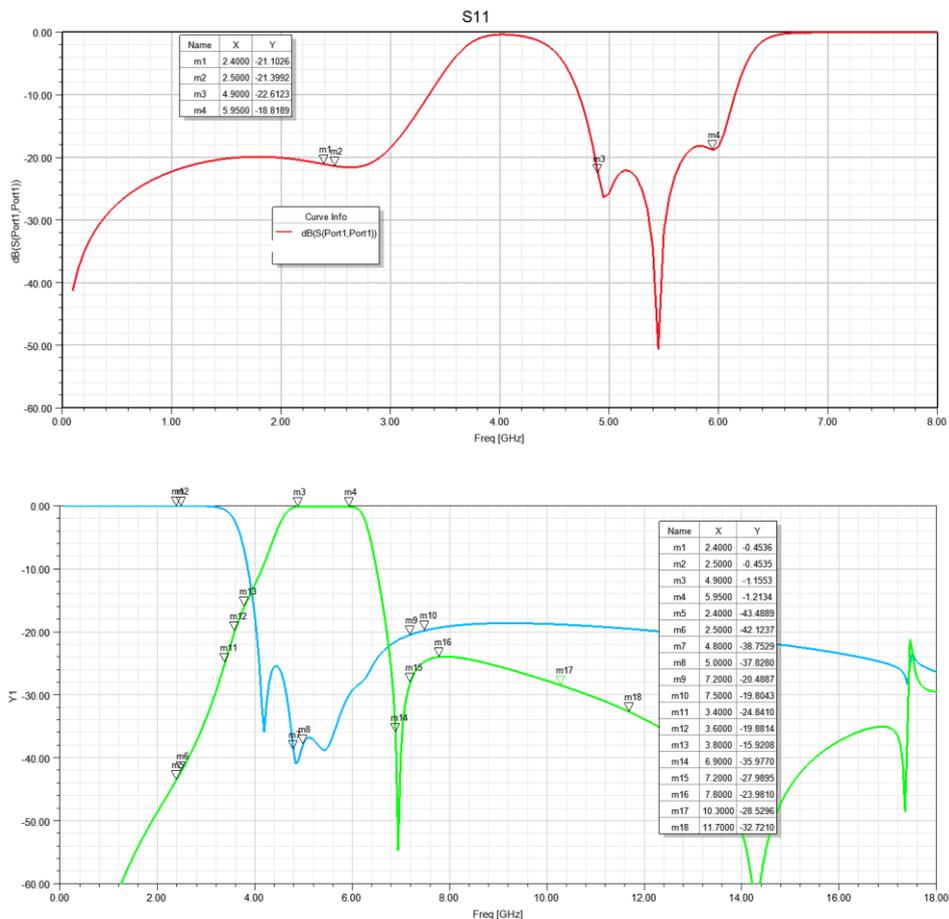


PIN	Connection	PIN	Connection
P1	GND	P4	Low Port
P2	Common Port	P5	GND
P3	GND	P6	Higher Port

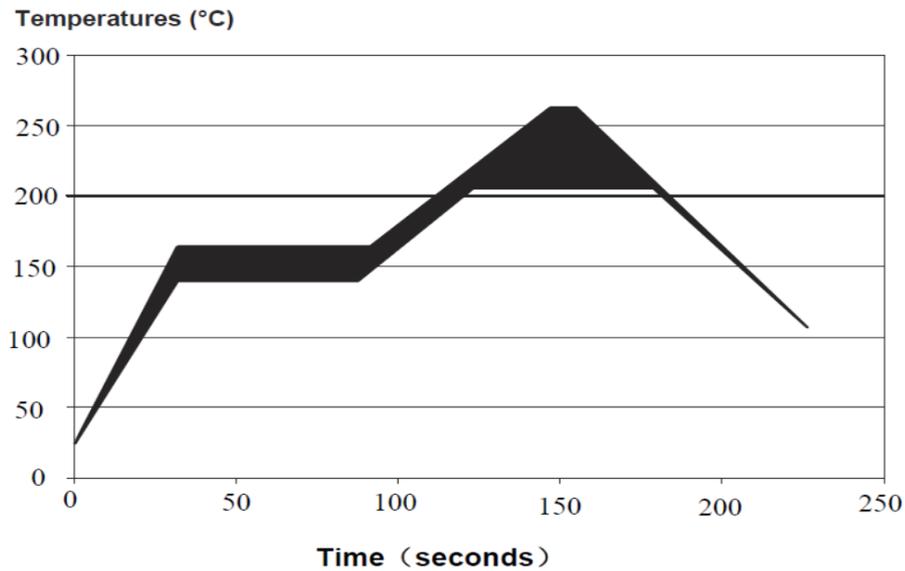
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.6 ± 0.10
	W	0.8 ± 0.10
	T	0.6MAX
	A	0.3 ± 0.05
	B	0.2 ± 0.05
	C	0.25 ± 0.05
	D	0.2 ± 0.05
	E	0.15 ± 0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.